Lam Research Corporation Advances CMP Edge Control With New XD™ Platen

Lam Research Corporation Advances CMP Edge Control With New XD Platen

New technology enables higher yields by extending process control capability to within 2 mm of the wafer's edge.

FREMONT, Calif., November 5, 2001 - Lam Research Corporation (Nasdaq: LRCX) today introduced the new XD (eXtra Die) Platen for Lam's 200 mm Teres® CMP system. The advanced technology extends reliable control for CMP processes to within 2 mm of the wafer's edge, enabling higher yields. Within-wafer nonuniformity of less than 3 percent with 2 mm edge exclusion has been routinely demonstrated.

According to Dr. Chris Raeder, senior member, technical staff, at AMD's Fab 25, "Teres has always provided superior center-to-edge process control because of the platen's radial tuning capability, which we employed extensively to develop a robust direct STI process. Now, we are using the new platen to improve die yield."

"Achieving CMP process control at the wafer's edge is difficult because of local variations in incoming film thickness profiles. In addition, polish pad compression and rebound characteristics change at the wafer's edge, further complicating local control of material removal. The new XD Platen design extends the patented technology of Teres' air bearing platen to overcome these issues," stated Rod Kistler, managing director of technology for Lam's CMP/Clean Products Group.

"Overcoming the integration challenges posed by copper-low k processes not only requires superior edge control but also the ability to decouple removal rate and planarization from within-wafer nonuniformity. Pairing advanced edge control technology with Teres' well-known ability to customize removal profiles extends integration capability beyond the 70 nanometer node," Kistler added.

The XD Platen is available as an upgrade to installed 200 mm Teres systems and is available for new products shipping from Lam's factory.

This press release contains certain forward-looking statements which are subject to the Safe Harbor provisions created by the Private Securities Litigation Reform Act of 1995. Such forward-looking statements include those relating to process and machine performance, future cost reductions, the commercial availability of products and product features and prospective die yields, among others. Such statements are based on current expectations and are subject to risks, uncertainties, and changes in condition, significance, value and effect including those risks detailed in documents filed with the Securities and Exchange Commission, including specifically the report on Form 10-K for the year ended June 24, 2001, and the Form 10-Q for the quarter ended March 25, 2001, which could cause actual results to vary from expectations. The company undertakes no obligation to update the information in this Press Release.

Lam Research Corporation is a leading supplier of wafer fabrication equipment and services to the world's semiconductor industry. Lam's common stock trades on the Nasdaq National Market under the symbol LRCX. The Company's World Wide Web address is http://www.lamrc.com

---

https://newsroom.lamresearch.com/2001-11-05-Lam-Research-Corporation-Advances-CMP-Edge-Control-With-New-XD-153-Platen